

OL-PCF8811U

Wire bond die; 248 bonding pads

10 February 2016

Package information

1. Package summary

Terminal position code	U (upper)
Package type descriptive code	UC
Package type industry code	UC
Package style descriptive code	UC (uncased chip)
Package style suffix code	NA (not applicable)
Package body material type	X (other)
Mounting method type	S (surface mount)
Issue date	14-12-2011

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	-	-	12.14	-	mm
E	package width	-	-	1.86	-	mm
e	nominal pitch	-	-	70	-	µm
n ₂	actual quantity of termination	-	-	248	-	



2. Package outline

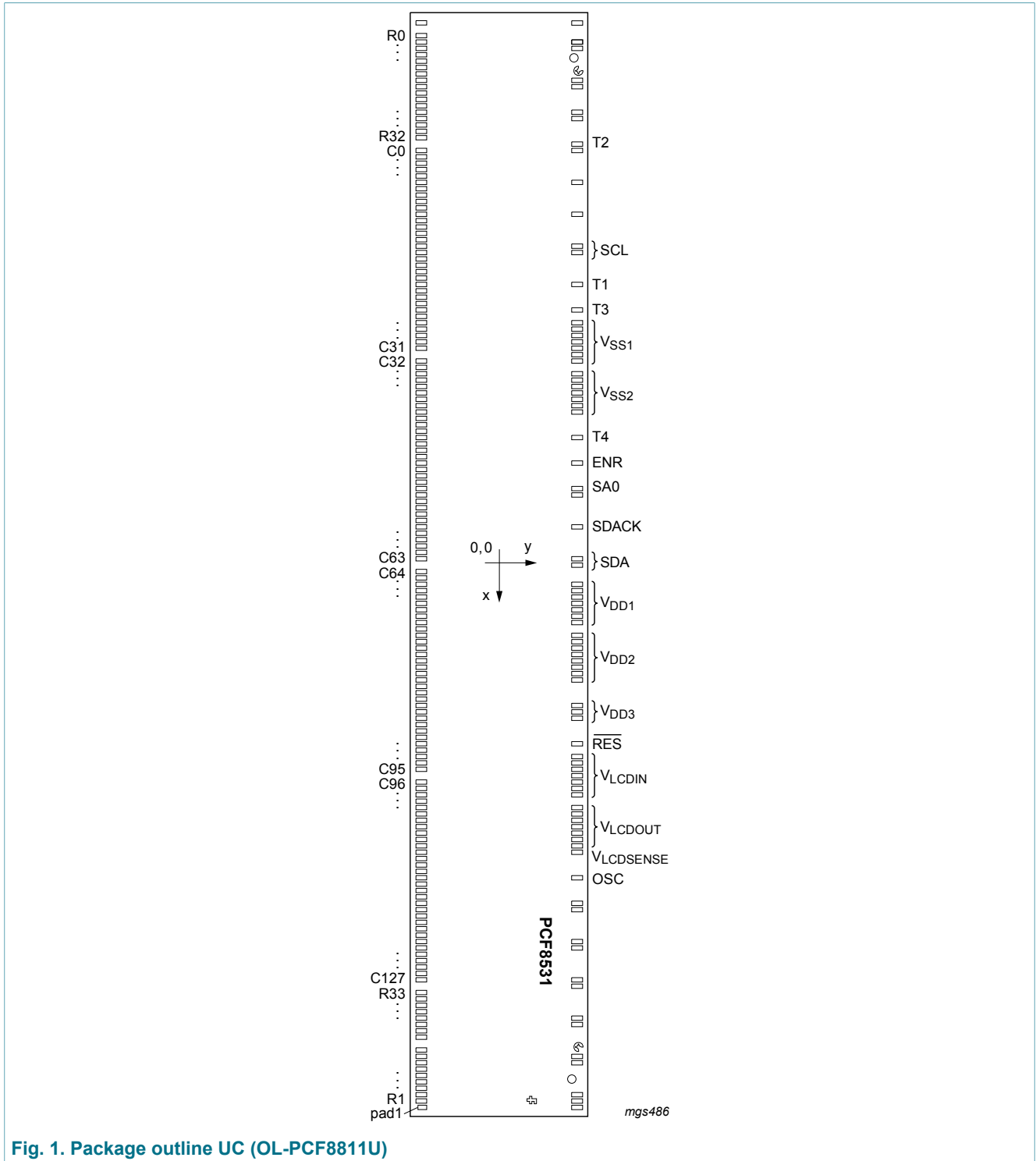


Fig. 1. Package outline UC (OL-PCF8811U)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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